

Migdal Ha'emek, Israel, June, 2022 – PCB Technologies Ltd.

## **PCB Technologies launches iNPACK™, a Miniaturization, and Advanced Packaging solution Provider**

iNPACK focuses on advanced microelectronics packaging technology for improved signal integrity and increased functionality

PCB Technologies introduces iNPACK, an advanced heterogeneous integration provider of System-in-Package (SiP) solutions. iNPACK, launching in July, is a subsidiary of PCB Technologies, an industry leader in PCB fabrication, assembly, and box builds.

iNPACK focuses on high-end technology that contributes to improved signal integrity and reduces unwanted inductance effects. This is accomplished through the use of powerful components that increase functionality, and utilize embedded coins for heat dissipation. iNPACK provides SiP, semiconductor packaging, organic substrates (25-micron lines and 25-micron spacing), and 3D, 2.5D, and 2D packaging solutions, to many of the world's most demanding industries including aerospace, defense, medical, consumer electronics, automotive, energy, and communications.

With heavy investments in new equipment and software, iNPACK provides a unique solution for customers worldwide looking for quick turn fabrication (delivery in 6 months), and the ability to quickly ramp to mass production, all under one roof.

**Jeff De Serrano**, PCB Technologies' President for North America said: "The new company incorporates innovative interconnects as part of its substrates and micro assembly process capabilities. Our technological solutions can more than double the electronic functionality in the same form factor, and create substrate-like PCBs. To top it off, our lead times are only six months long. The goal is to support our customers from design concept to production, all under the same roof, while utilizing unified design rules."

PCB Technologies is an industry leading manufacturer of HDI Rigid, Rigid-Flex and Flex PCBs for Analog, RF, and High Speed Digital designs.

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